

**CLAIM LISTING**

This listing of claims will replace all prior versions, and listings of claims in the application:

**IN THE CLAIMS**

1. (Previously Presented) A lid for an integrated circuit, said lid comprising:
  - i. a recessed portion adapted to receive a die of said integrated circuit;
  - ii. a foot portion having a surface extending a width from said recessed portion and adapted to be coupled to a substrate of said integrated circuit; and
  - iii. a plurality of recesses formed at the edges of said foot portion, said foot portion having a reduced width at said plurality of recesses.
2. (Original) The lid of claim 1 wherein each recess of said plurality of recesses comprises a semi-circle.
3. (Original) The lid of claim 1 wherein each recess of said plurality of recesses comprises a beveled edge.
4. (Original) The lid of claim 1 wherein each recess of said plurality of recesses comprises a partial conical surface.
5. (Previously Presented) The lid of claim 1 further comprising corners between two end recesses on adjacent sides of said lid.

6. (Currently Amended) An integrated circuit having a lid, said integrated circuit comprising:
  - i. a substrate;
  - ii. a die positioned on said substrate; and
  - iii. a lid having a recessed portion adapted to receive said die and a foot portion having a planar surface coupled to said substrate by a bonding agent, said lid comprising a plurality of recesses formed adjacent to said planar surface at the edges of said foot portion; and
  - iv. a plurality of bond posts formed within the plurality of recesses by the bonding agent.
7. (Original) The integrated circuit of claim 6 wherein said plurality of recesses expose said bonding agent.
8. (Original) The integrated circuit of claim 6 wherein said plurality of recesses comprises beveled edges.
9. (Original) The integrated circuit of claim 8 wherein said beveled edges of said plurality of recesses receive a portion of said bonding agent.
10. (Original) The integrated circuit of claim 6 further comprising an adhesive between said lid and said die.
11. (Canceled)
12. (Canceled)

13. (Currently Amended) An integrated circuit having a lid, said integrated circuit comprising:

- i. a substrate;
- ii. a die positioned on said substrate; and
- iii. a lid having a recessed portion adapted to receive said die and a foot portion having a planar surface coupled to said substrate by a solder bond, said lid comprising a plurality of recesses formed adjacent to said planar surface at the edges of said foot portion; and
- iv. corners between two end recesses on adjacent sides of said lid.

14. (Original) The integrated circuit of claim 13 wherein said solder bond comprises a surface mount solder reflow.

15. (Original) The integrated circuit of claim 13 further comprising an adhesive between said lid and said die.

16. (Original) The integrated circuit of claim 13 wherein each recess of said plurality of recesses comprises a partial conical surface.

17.-27. (Canceled)

28. (Original) A method of securing a lid to an integrated circuit, said method comprising the steps of:

- i. providing a lid having a plurality of thru holes extending through the foot portion of the lid, wherein said thru holes are conical shaped;
- ii. applying a bonding agent to a substrate of said integrated circuit; and
- iii. positioning said lid on said substrate such that said bonding agent extends into said thru holes.

29. (New) The integrated circuit of claim 6 wherein the bonding agent is an adhesive.